The current column covers peer-reviewed articles published since 2014 on novel materials, packages, components, and 3-D integration. Novel materials include low- and high-k dielectrics, while packaging/3-D integration encompasses topics such as through-silicon vias, multichip modules, packaging materials, components, and so on. Note that inclusion in the list does not vouch for the article’s quality, and category sorting is by no means strict.

If you wish to share an interesting recently published peer-reviewed article with the community, please forward the citation to the e-mail address listed above and I will try to include it in future installments.

Entries are listed in alphabetical order by first author, then title (in bold), journal, year, volume, and first page. Note that in some cases bracketed text is inserted into the title to provide clarity about the article subject.

- S. Ogawa, R. Asahara, Y. Minoura, et al.: “Insights into Thermal Diffusion of Germanium and Oxygen Atoms in HfO₂/GeO₂/Ge Gate Stacks and Their Suppressed


